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WPI Acc No: 1993-237349/199330
Related WPI Acc No: 1993-237352
XRAM Acc No: C93-105684
XRPX Acc No: N93-182338
  Negative type photosensitive compsn., for photoresist, etc. - contains
  water insol. and alkali soluble resin, acid generating cpd., cpd. capable
  of crosslinking and base generating cpd. and has high sensitivity and
  resolution
Patent Assignee: FUJI PHOTO FILM CO LTD (FUJF )
Inventor: AOAI T; KOKUBO T
Number of Countries: 002 Number of Patents: 002
Patent Family:
                           Date
                  Kind
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Patent No
                                                                19911203 199330 B
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                         19930625 JP 91344085
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                         19961119 US 92985262
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US 5576143
                   Α
Priority Applications (No Type Date): JP 91344085 A 19911203; JP 91344112 A
  19911203
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                          31 G03F-007/038
JP 5158239
                 Α
                          19 G03C-001/492
US 5576143
                  Α
Abstract' (Basic): JP 5158239 A
          Compsn. contains: (A) a resin which is water insoluble and alkali
     soluble; (B) a cpd. which generates an acid due to the irradiation of active rays or radiation; (C) a cpd. which has at least one gp. capable of crosslinking due to the effect of an acid, and (D) a cpd. which
     generates a base at more than 50 deg.C.
     USE/ADVANTAGE - This photosensitive compsn. has high sensitivity and resolution. This compsn. is intended for use as a photoresist, esp., it is best fit for a micro-photoresist. Typically, it is used for
     a lithographic printing plate and the photoresist obtd. from this compsn. is not affected by varying conditions of processing after the
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exposure. It is fit for a light source having a short wavelength of a

Deep-UV area Dwg. 0/0